



WS1236M

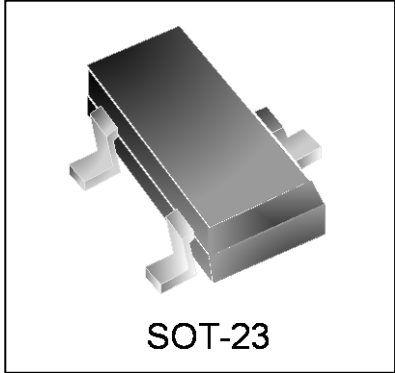
Transient Voltage Suppressor

Features

- 325 watts peak pulse power ($t_p = 8/20\mu s$)
- Protects two lines
- Low capacitance
- Low clamping voltage
- Solid-state silicon avalanche technology

IEC COMPATIBILITY (EN61000-4)

- IEC 61000-4-2 (ESD) $\pm 30kV$ (air), $\pm 30kV$ (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 13A (8/20 μs)



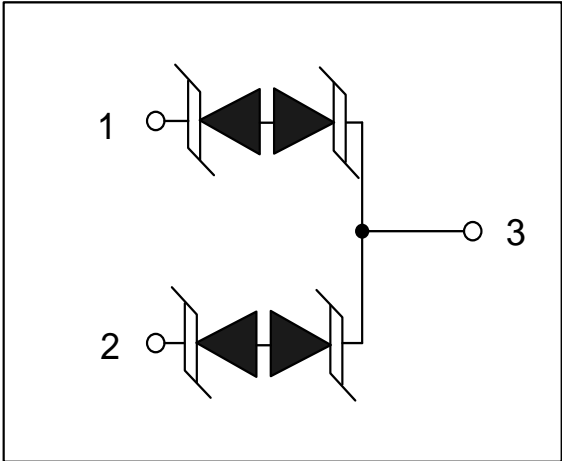
Mechanical Characteristics

- SOT-23 package
- Marking : Making Code
- Packaging : Tape and Reel
- RoHS Compliant

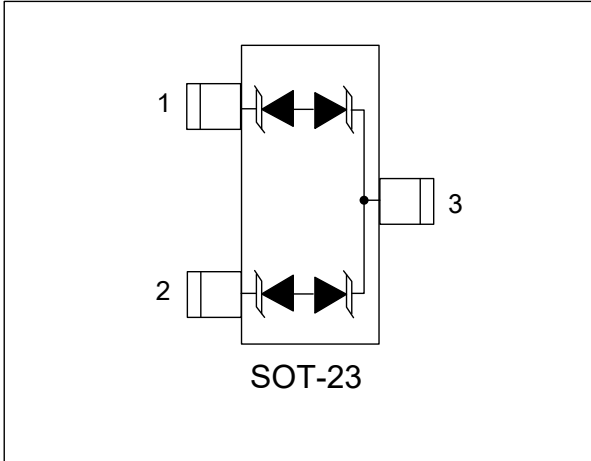
Applications

- Protection of RS-485 transceivers with extended common-mode range
- Security systems
- Automatic Teller Machines
- HFC systems
- Net works

Circuit Diagram



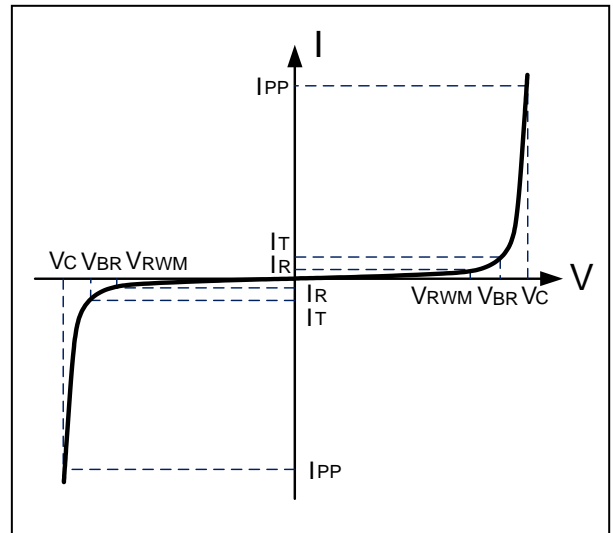
Schematic & PIN Configuration



Absolute Maximum Rating			
Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{PP}	325	Watts
Peak Pulse Current ($t_p = 8/20\mu s$)	I_{PP}	13	A
Operating Temperature	T_J	-55 to + 125	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Parameters (T=25°C)

Symbol	Parameter
I_{PP}	Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Reverse Stand-Off Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current



Electrical Characteristics

WS1236M									
			Pins 1 to 3 or 2 to 3			Pins 3 to 1 or 3 to 2			
Parameter	Symbol	Conditions	MIN	TYP	MAX	MIN	TYP	MAX	Units
Reverse Stand-Off Voltage	V_{RWM}				36			12	V
Reverse Breakdown Voltage	V_{BR}	$I_T = 1mA$	39			13.3			V
Reverse Leakage Current	I_R	$V_R = V_{RWM}$			500			500	nA
Clamping Voltage	V_C	$I_{PP} = 5A,$ $t_p = 8/20\mu s$		62	66		17.5		V
Clamping Voltage	V_C	$I_{PP} = 13A,$ $t_p = 8/20\mu s$					22	25	V
Dynamic Resistance ^{1,2}	R_{DYN}	TLP=0.2/100ns		0.08			0.25		Ω
Junction Capacitance	C_j	$V_R = 0V,$ $f = 1MHz$		20	25		20	25	pF
		$V_R = V_{RWM},$ $f = 1MHz$		6.5			15		pF

Notes : 1、 TLP Setting : $t_p=100ns, t_r=0.2ns, I_{TLP}$ and V_{TLP} sample window: $t_1=70ns$ to $t_2=90ns$.

2、 Dynamic resistance calculated from $I_{PP}=4A$ to $I_{PP}=16A$ using "Best Fit".

Typical Characteristics

Figure 1: Peak Pulse Power vs. Pulse Time

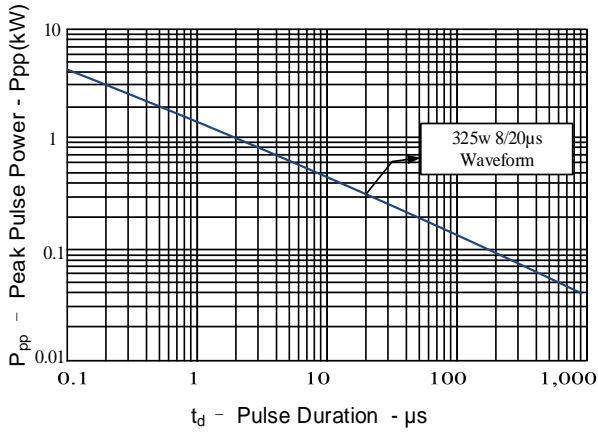


Figure 2: Power Derating Curve

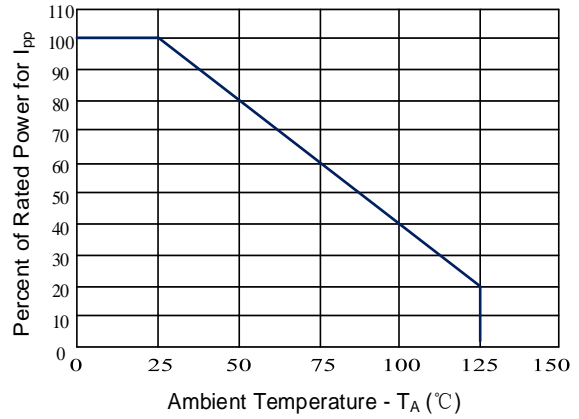


Figure 3: Clamping Voltage vs. Peak Pulse Current

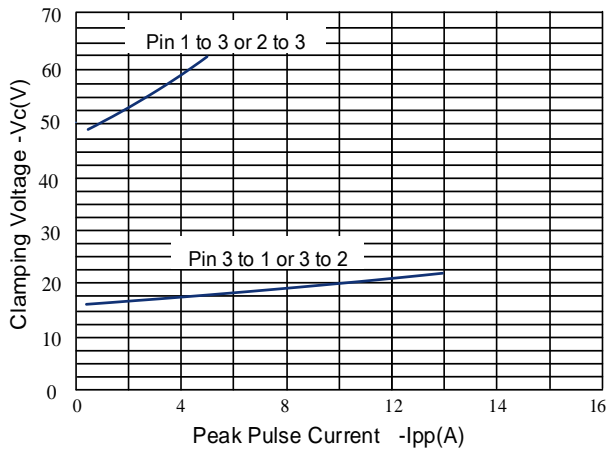


Figure 4: Normalized Junction Capacitance vs. Reverse Voltage

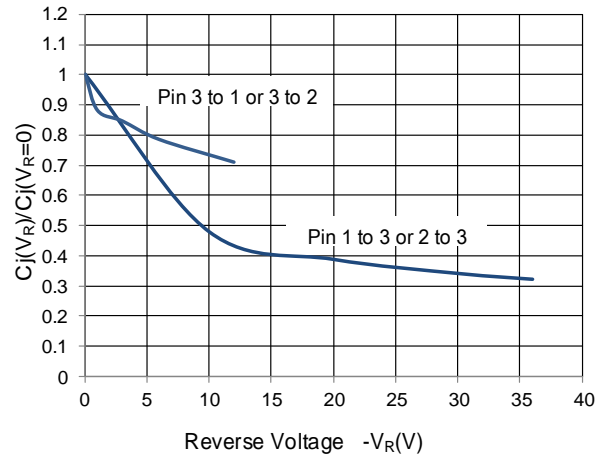


Figure 5: TLP I-V Curve (Pin 1 to 3 or 2 to 3)

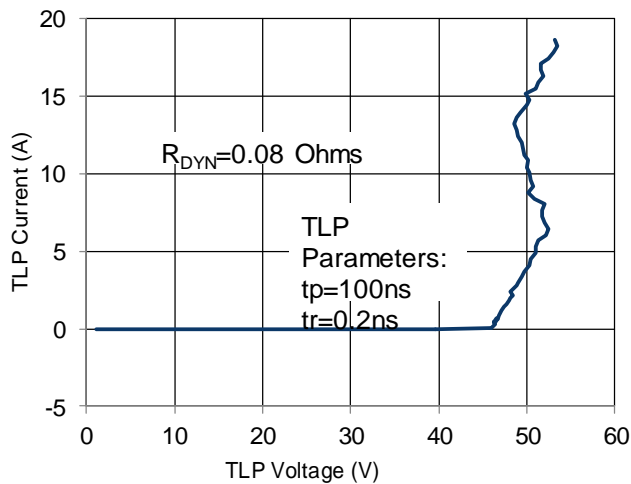
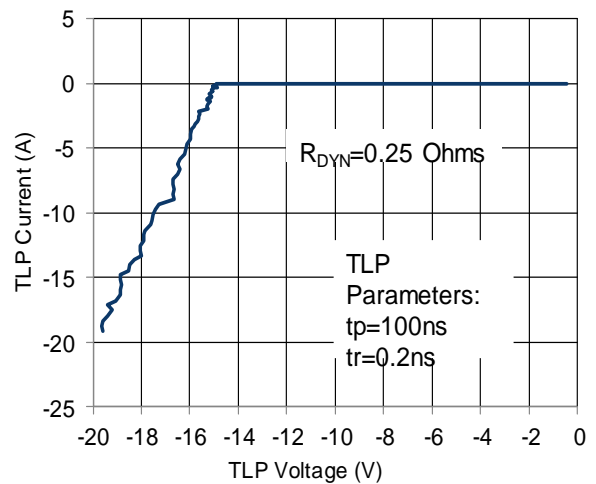
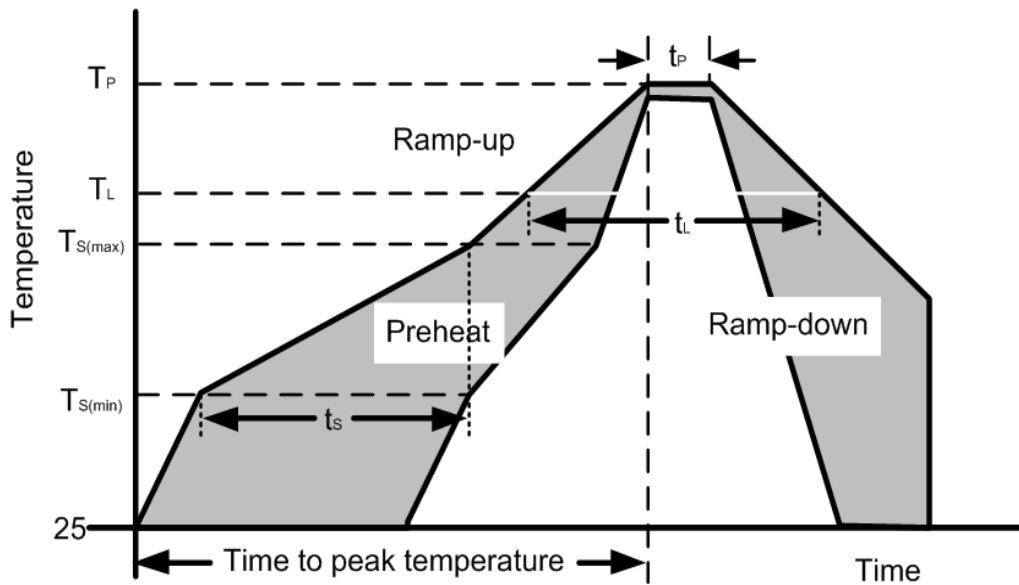


Figure 6: TLP I-V Curve (Pin 3 to 1 or 3 to 2)



Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	Temperature Min ($T_{S(min)}$)	150°C
	Temperature Max ($T_{S(max)}$)	200°C
	Time (min to max) (t_s)	60 – 190 secs
Average ramp up rate (Liquidus Temp) (T_L) to peak		5°C/second max
$T_{S(max)}$ to T_L —Ramp-up Rate		5°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		260+0/-5 °C
Time within actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		280°C



Outline Drawing – SOT-23

PACKAGE OUTLINE

SOT-23

SYMBOL	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.90	1.15	0.035	0.045
A1	0.00	0.10	0.000	0.004
A2	0.60	0.70	0.024	0.028
b	0.30	0.50	0.012	0.020
c	0.08	0.15	0.003	0.006
D	2.80	3.00	0.110	0.118
E	2.25	2.55	0.089	0.100
E1	1.20	1.40	0.047	0.055
e	0.95 BSC		0.037 BSC	
e1	1.80	2.00	0.071	0.079
L	0.30	0.50	0.012	0.020
θ	0	8°	0	8°

DIMENSIONS		
DIM	INCHES	MILLIMETERS
M	0.0795	2.02
C	0.0315	0.80
Z	0.111	2.82
e	0.037 BSC	0.95 BSC
e1	0.075 BSC	1.9 BSC
b	0.0315	0.80

Notes:
Controlling Dimension: Millimeter.

Marking Codes

Part Number	WS1236M
Marking Code	

Package Information

Qty: 3k/Reel

CONTACT INFORMATION

No.1001, Shiwan (7) Road, Pudong District, Shanghai, P.R.China.201207

Tel: 86-21-68969993 Fax: 86-21-50757680 Email: market@way-on.com

WAYON website: <http://www.way-on.com>

For additional information, please contact your local Sales Representative.

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Specifications are subject to change without notice.
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.
Users should verify actual device performance in their specific applications.